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(54) Title: A STRIPPABLE HYBRID TRAY SYSTEM FOR ELECTRONIC DEVICES

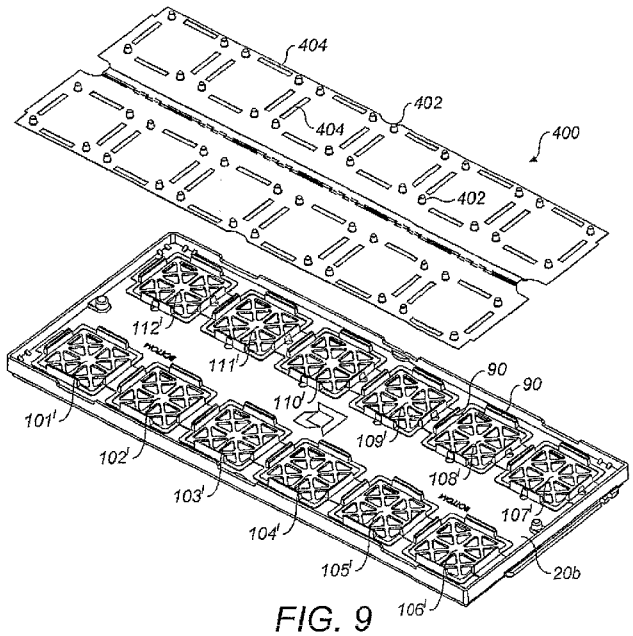


FIG. 9

(57) Abstract: A component tray system comprises a component tray (10) having pockets (101-112; 101'-112'), such as a standard JEDEC tray, and a thermoformed sheet (400) removably attached to either a top or a bottom surface (20a; 20b) of the tray. The sheet (400) includes thermoformed protrusions (402) for altering at least the depth of the pockets (101'-112'). During manufacture of components (1000), first components (1000a) of a first size, such as bare substrates, are loaded into the pockets in the tray (10) and held securely in place by the protrusions (402) of the sheet. After a manufacturing operation, the first components (1000a) are transformed into second components, larger than the first components. The sheet (400) is removed so that these larger second components can be accommodated in the pockets (101-112; 101'-112'). This arrangement provides that a single tray can be used throughout a manufacturing process, yet can be adapted to snugly accommodate components of varying sizes throughout.

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